

WIRE BONDING PACKAGE

Abstract

A wire bonding package has a housing having a plurality of pins, a circuit board installed inside the housing and having at least a trace connected to a pin of the housing, at least a die installed on the circuit board and having a plurality of bonding pads, and at least a bonding line connected between a bonding pad of the die and the trace of the circuit board so that the bonding pad of the die is electrically connected to the pin of the housing.